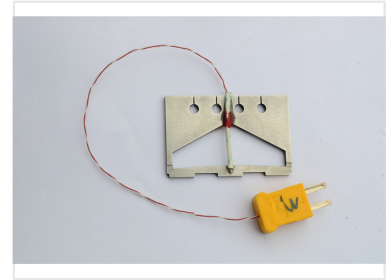
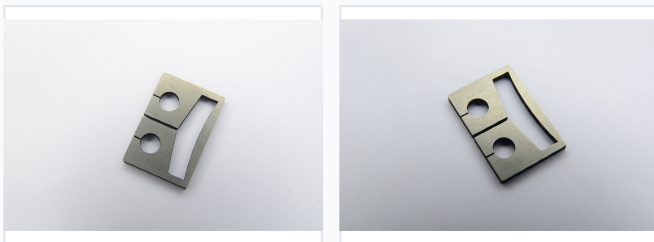


High Precision HOTBAR Bonding Tip for Microelectronics

This high-precision HOTBAR bonding tip is designed for accurate and reliable bonding processes. It ensures optimal heat distribution and precise alignment during microelectronic assembly.



ADDITIONAL IMAGES



Product Overview

Precision Engineering for Microelectronics

This high-precision HOTBAR bonding tip is meticulously crafted to deliver reliable and accurate bonding processes in advanced microelectronic assembly. Engineered for exceptional thermal conductivity and durability, the tip ensures uniform heat distribution, which minimizes the risk of thermal damage to sensitive components. Its robust design, featuring integrated alignment mechanisms, guarantees consistent performance and repeatability in demanding manufacturing environments.

Technical Specifications

Design Features

- Circular cutouts with connecting slits
- Central channel for precise positioning
- Integrated alignment holes
- Durable metal frame construction
- Insulated wire connection

Application Focus

Microelectronics Assembly, Electronics Manufacturing, Precision Bonding

Performance Metrics

Performance Highlights

1 Uniform

Heat Distribution

1 High

Alignment Accuracy

Material Quality

High Thermal Conductivity • Durable Construction